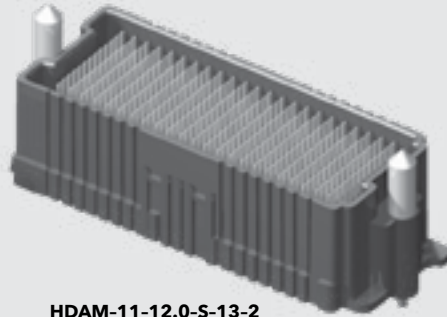
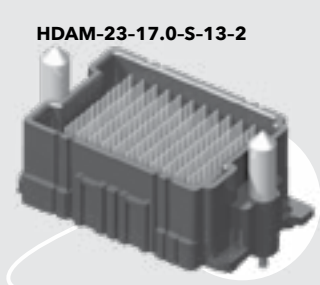




(2.00 mm) .0787"



HDAM-11-12.0-S-13-2



HDAM-23-17.0-S-13-2

HDAM SERIES

# RUGGED ELEVATED HIGH-DENSITY ARRAY

## SPECIFICATIONS

For complete specifications and recommended PCB layouts see [www.samtec.com?HDAM](http://www.samtec.com?HDAM)

**Insulator Material:**

Black LCP

**Contact Material:**

Copper Alloy

**Plating:**

Au or Sn over 50 μ" (1.27 μm) Ni

**Current Rating:**

3.4 A per pin (6 adjacent pins powered)

**Operating Temp Range:**

-55 °C to +125 °C

**Working Voltage:**

200 VAC

**Mated Cycles:**

100

**RoHS Compliant:**

Yes

**Lead-Free Solderable:**

Yes

Mates with:  
HDAF

Intermateable with  
Molex HD Mezz

Open-pin-field for  
Single-Ended or  
Differential Pair  
configurations

299, 195  
and 143 pins

Lead-Free  
Solder Charge

Elevated stack heights  
of 20 mm, 25 mm,  
30 mm and 35 mm

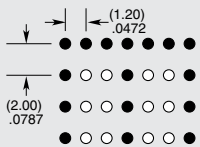
## RECOGNITIONS

For complete scope of recognitions see [www.samtec.com/quality](http://www.samtec.com/quality)



FILE NO. E111594

## DIFFERENTIAL APPLICATIONS



ARRAY	PAIR COUNT*
11x13	44
15x13	60
23x13	92

\*2:1 S:G Ratio

## ALSO AVAILABLE (MOQ Required)

- Tin-Lead Solder Charge
- Other platings

**Notes:**  
HD Mezz is a trademark of Molex Incorporated

Some lengths, styles and options are non-standard, non-returnable.



-11, -15, -23

Specify  
LEAD  
STYLE  
from  
chart

-S  
= 30 μ" (0.76 μm)  
Gold on  
contact area,  
Matte Tin  
on tails and  
guide pins

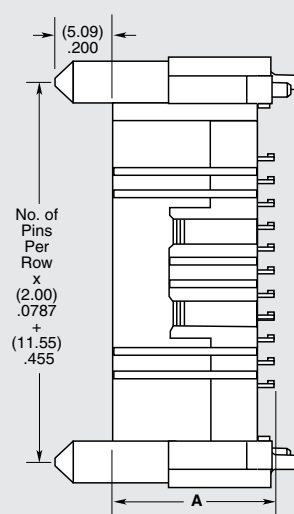
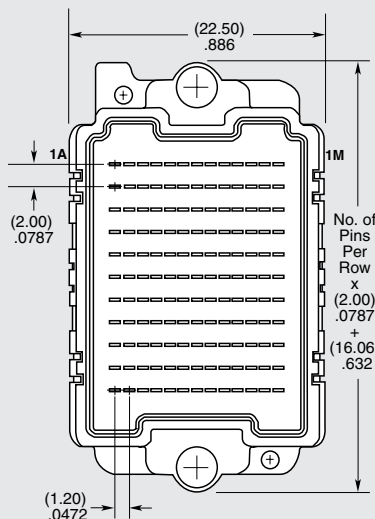
-2  
= Lead-Free  
Tin Alloy 95.5% Sn/  
3.8% Ag/0.7% Cu  
Solder Charge

-P  
= Pick &  
Place Pad

Leave blank for  
tray packaging

-TR  
=Tape & Reel

-FR  
= Full Reel  
Tape & Reel  
(must order max.  
quantity per reel;  
contact Samtec  
for quantity  
breaks)



LEAD STYLE	A
-12.0	(14.41) .567
-17.0	(19.41) .764